

Crystal Defects

Perfect crystal - every atom of the same type in the correct equilibrium position
(does not exist at $T > 0$ K)

Real crystal - all crystals have some imperfections - defects,
most atoms are in ideal locations, a small number are out of place

- Intrinsic defects – present for thermodynamic reasons
- Extrinsic defects – not required by thermodynamics, can be controlled by purification or synthetic conditions

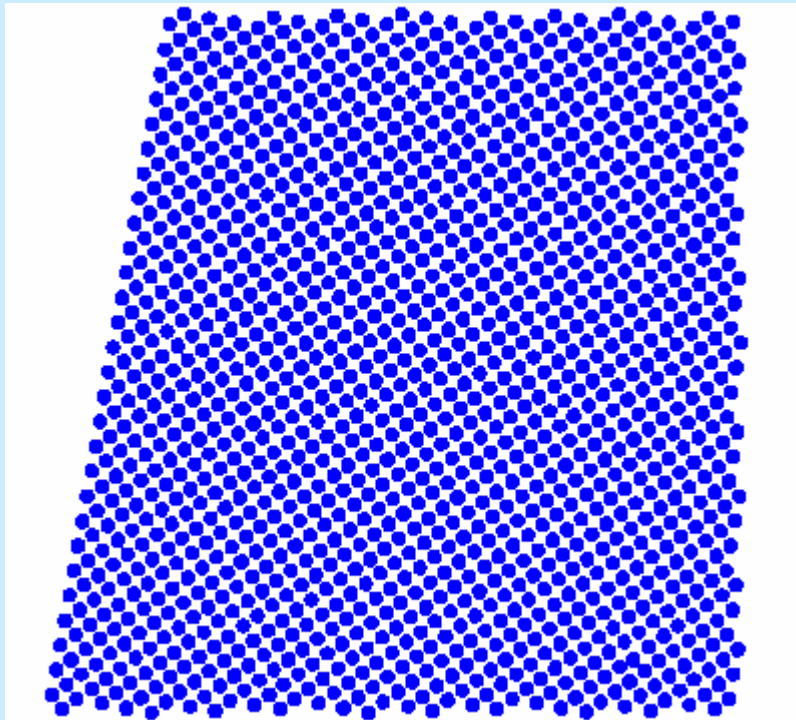
- Chemical defects (foreign atom, mixed crystals, nonstoichiometry)
- Geometrical defects (vacancy, interstitials, dislocations, boundaries, surface)

Defects dominate the material properties, contribute to:

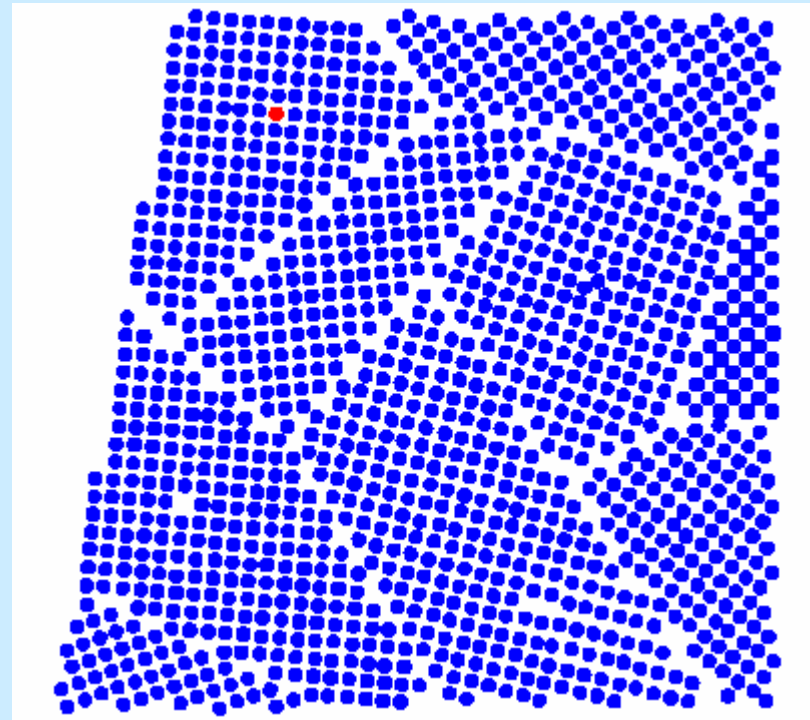
Mechanical, Chemical, Electrical, Diffusion properties
can be added intentionally

Crystal Defects

Perfect crystal



Real crystal



Classes of Crystal Defects

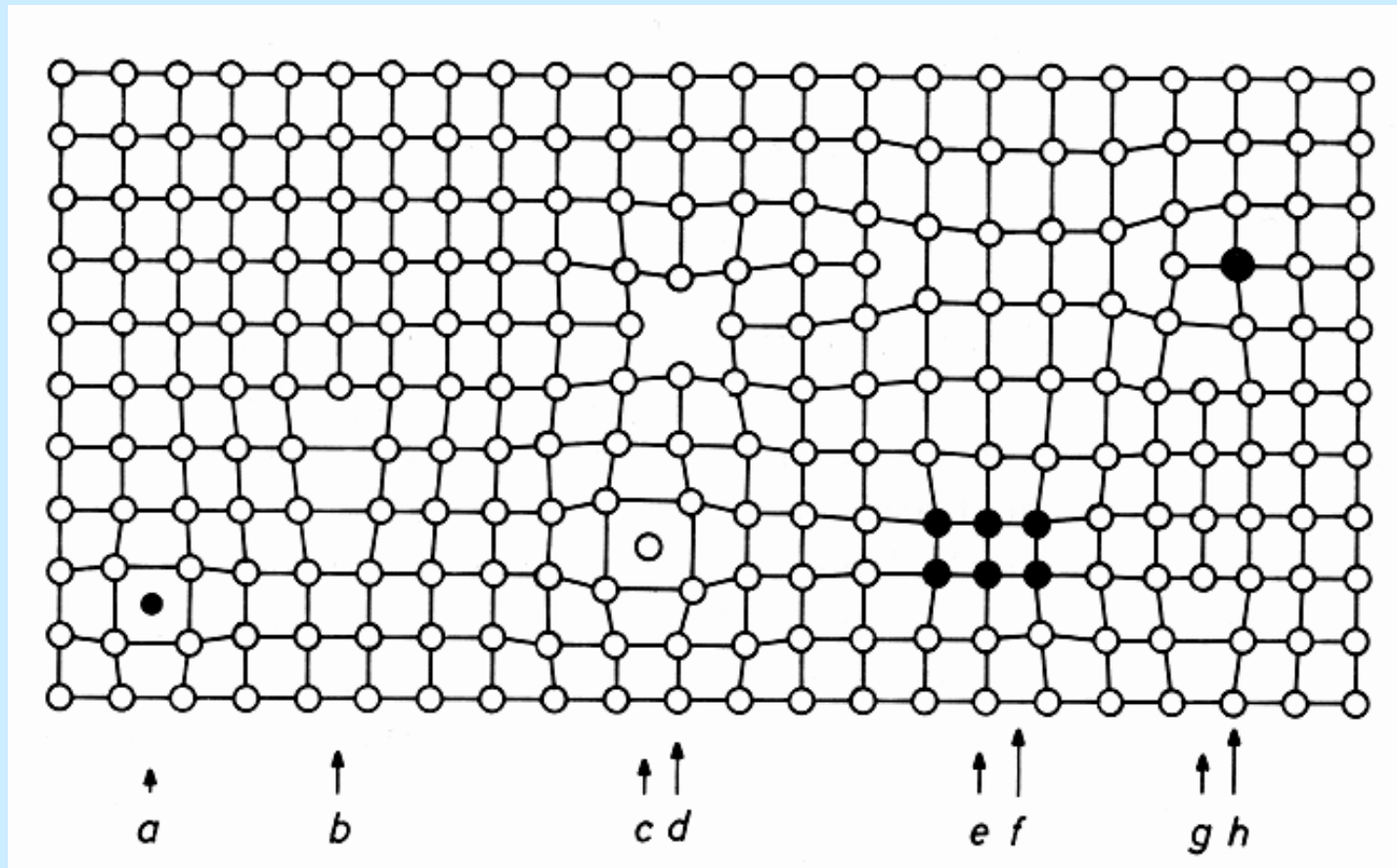
Point defects (0D) places where an atom is missing or irregularly placed in the lattice structure – lattice vacancies, self-interstitial atoms, substitution impurity atoms, interstitial impurity atoms

Linear defects (1D) groups of atoms in irregular positions – dislocations

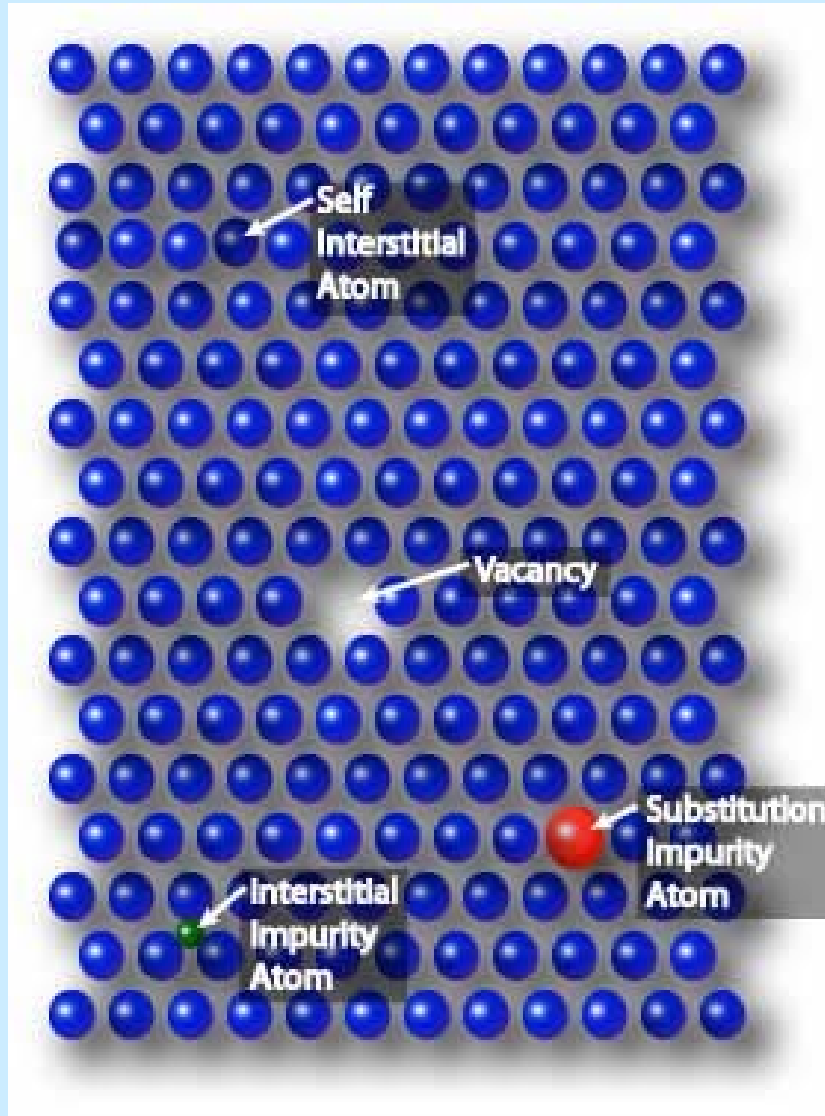
Planar defects (2D) interfaces between homogeneous regions of the material - grain boundaries, stacking faults, external surfaces

Volume defects (3D) spaces of foreign matter – pores, inclusions

Classes of Crystal Defects



Point Defects – Metals

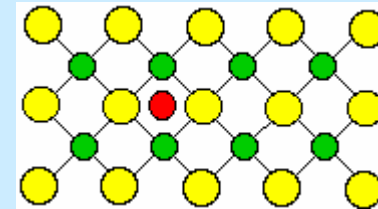
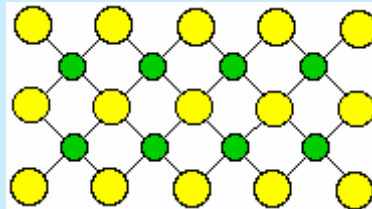


Point defects - an atom is missing or is in an irregular position in the lattice

- self interstitial atoms
- interstitial impurity atoms
- substitutional atoms
- vacancies

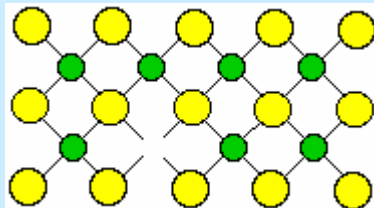
Point Defects – Ionic Compounds

perfect crystal lattice AB

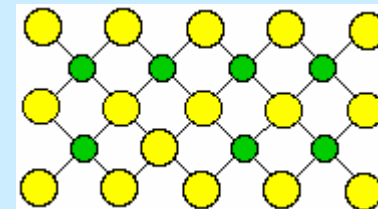
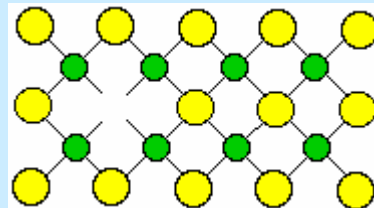


interstitial impurity

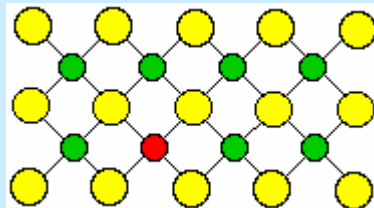
cation vacancy



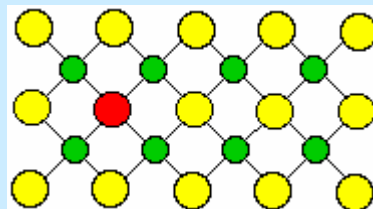
anion vacancy



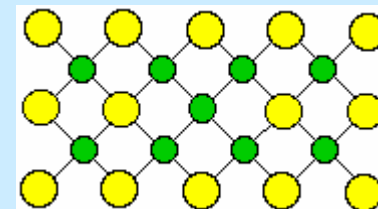
B_A antisite defect



substitution of a cation



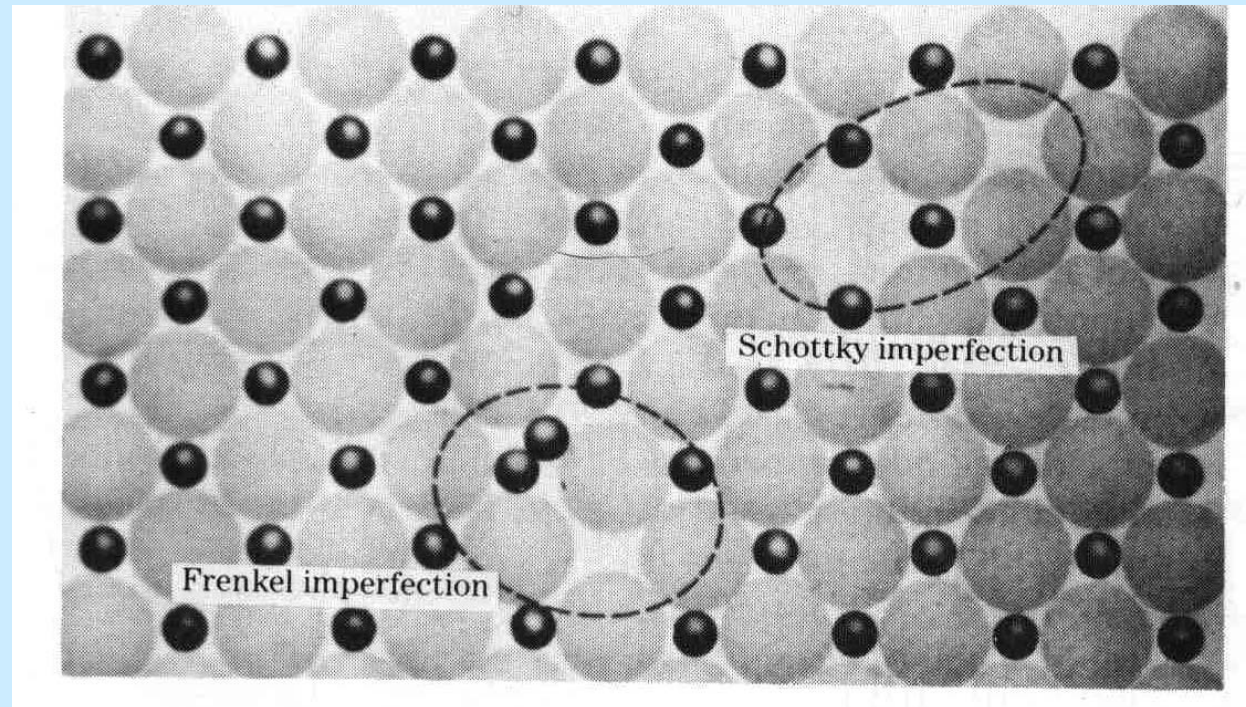
substitution of an anion



A_B antisite defect

Types of Point Defects in Ionic Compounds

- Vacancy
- Interstitial
- Substitutional
- Frenkel
- Schottky



Schottky: a pair of vacancies, missing cation/anion moved to the surface

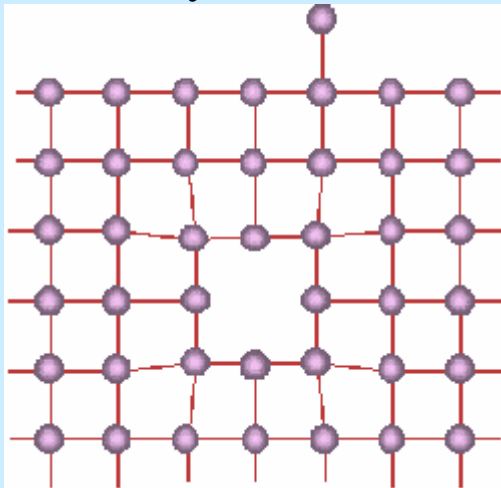
Frenkel: ions moved to interstitial positions, vacancies

Point Defects

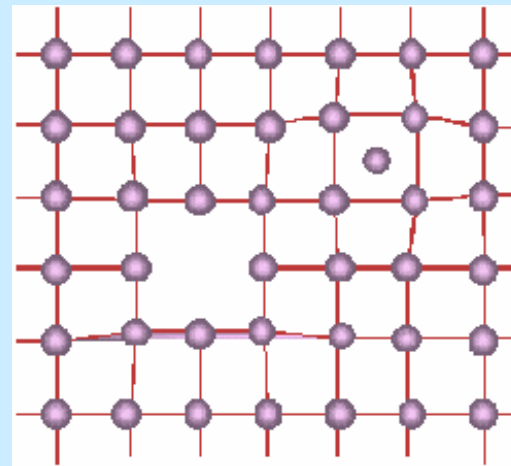
Schottky - equal numbers of vacancies at both A and B sites preserving charge balance. Encountered more commonly when metal ions are able to easily assume multiple oxidation states.

Frenkel - encountered in open structures (wurtzite, sphalerite, etc) where coordination numbers are low and open structure provides room for interstitial sites to be occupied

Schottky



Frenkel



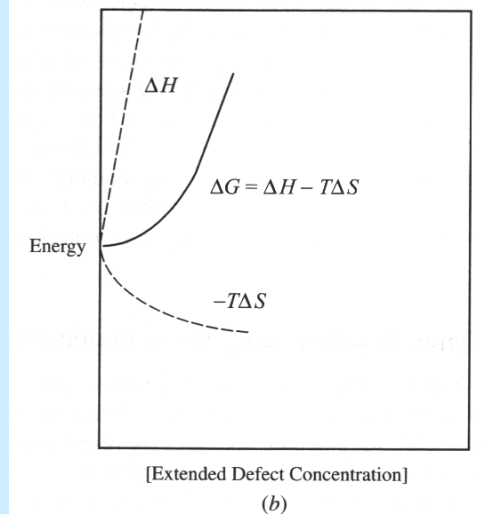
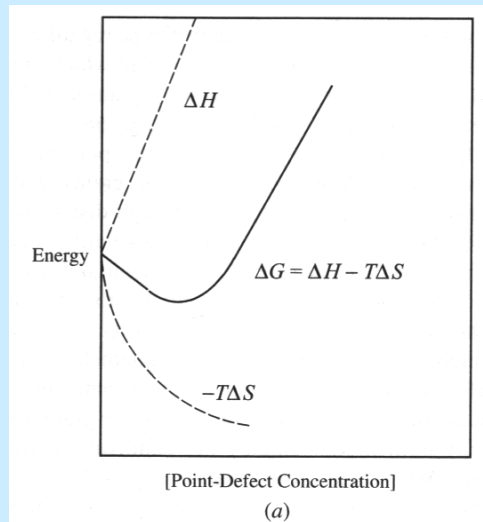
Vacancies

- There are naturally occurring vacancies in all crystals
- Equilibrium defects – thermal oscillations of atoms at $T > 0$ K
- The number of vacancies increases as the temperature goes up
- The number of vacancies

$$N_v = N \exp(-\Delta H^a/RT)$$

- N is the total number of sites in a crystal
- N_v is the number of vacancies
- ΔH^a is the activation energy for the formation of a vacancy
- R is the gas constant
- N_v goes up exponentially with temperature T

Crystal Energies



**Point defects = equilibrium concentration,
Enthalpy is positive, configurational entropy positive
Minimum on free energy**

**Extended defects = no equilibrium concentration,
Enthalpy is HIGHLY positive, configurational
entropy cannot outweigh, no minimum on free
energy**

Metastable – dislocations, grain boundaries, surface

Heating - minimize free energy:

polycrystalline → single crystal grain growth

Grains with high dislocation density consumed

Atoms move across grain boundary

Interstitial Atoms

- An atom must be fairly small to fit into the interstitial voids
- Hydrogen and Helium can diffuse rapidly through metals by moving through the interstitial voids
- Interstitial Carbon is used to strengthen iron - it distorts the matrix
- The ratio of r/R is 0.57 – therefore it needs an octahedral hole
- There are octahedral and tetrahedral holes in both FCC and BCC – however the holes in BCC are not regular polyhedra
- The solubility of Carbon in FCC iron is much higher than in BCC iron

Typical point defects in crystals

Alkali halides	Schottky (cations and anions)
Alkaline earth oxides	Schottky (cations and anions)
Silver halides	Frenkel (cations)
Alkaline earth fluorides	Frenkel (anions)

Typical activation energies for ion diffusion

Na⁺ in NaCl	~ 0,7 eV
Cl⁻ in NaCl	~ 1 eV
Schottky pair	~ 2,3 eV

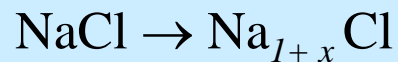
(1 eV/molecule = 96.49 kJ/mol)

Extrinsic Defects

The addition of the dopant (an impurity) into a perfect crystal = point defects in the crystal

NaCl heated in Na vapors

Na is taken into the crystal and changes the composition



Na atoms occupy cation sites

an equivalent number of unoccupied anion sites

Na atoms ionize, Na^+ ions occupy the cation sites,

the electrons occupy the anion vacancies – F centers – color

This solid is now a non-stoichiometric compound as the ratio of atoms is no longer the simple integer

Non-stoichiometric Compounds

Vanadium oxide

varies from $\text{VO}_{0.79}$ to $\text{VO}_{1.29}$

other examples: TiO_x , Ni_xO , UO_x and Li_xWO_3

Covalent compounds - held together by very strong covalent bonds which are difficult to break, do not show a wide range of composition

Ionic compounds - do not show a wide range because a large amount of energy is required to remove / add ions

non-stoichiometry can be caused by doping or by a multi-valent element

Non-stoichiometric Compounds

non-stoichiometric ionic crystals

a multi-valent element - changes in the number of ions can be compensated for by changes in the charge on the ions, therefore maintaining charge balance but changing the stoichiometry

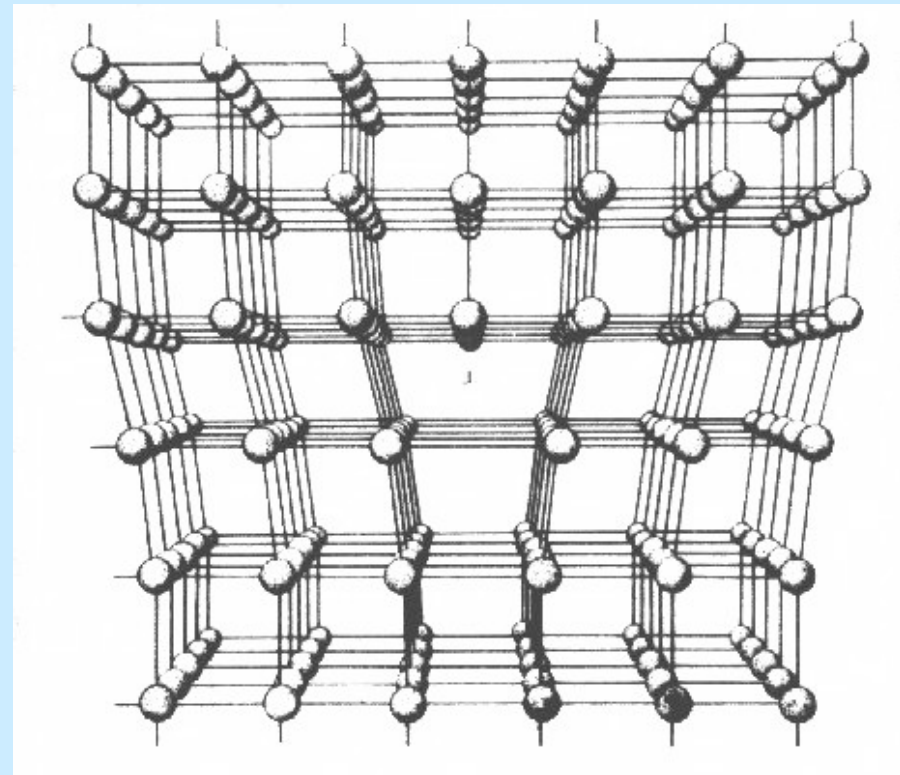
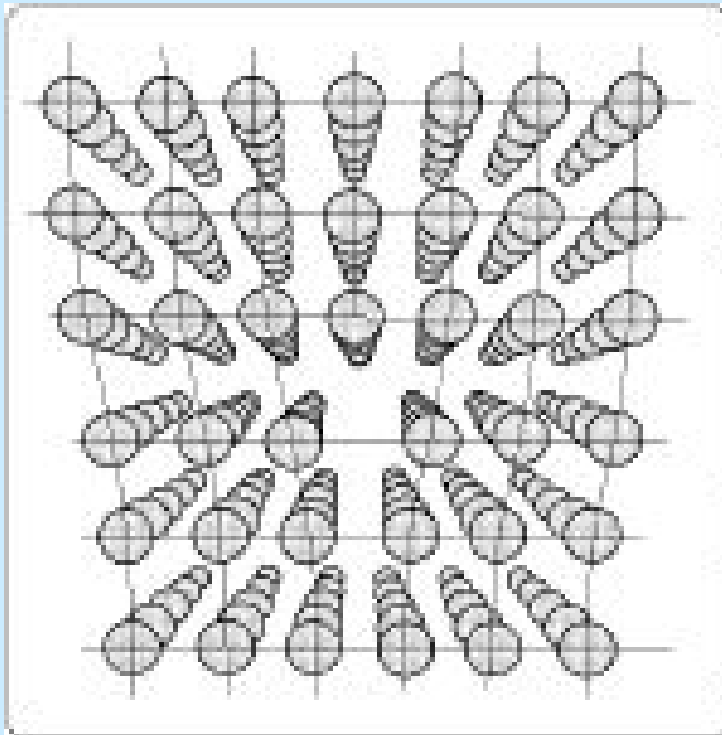
non-stoichiometric compounds have formulae with non-integer ratios and can exhibit a range of compositions.

They are formed by introducing an impurity (doping) or by the ability of an element to show multi-valent character. The electronic, optical, magnetic and mechanical properties of non-stoichiometric compounds can be controlled by varying their composition.

Dislocations

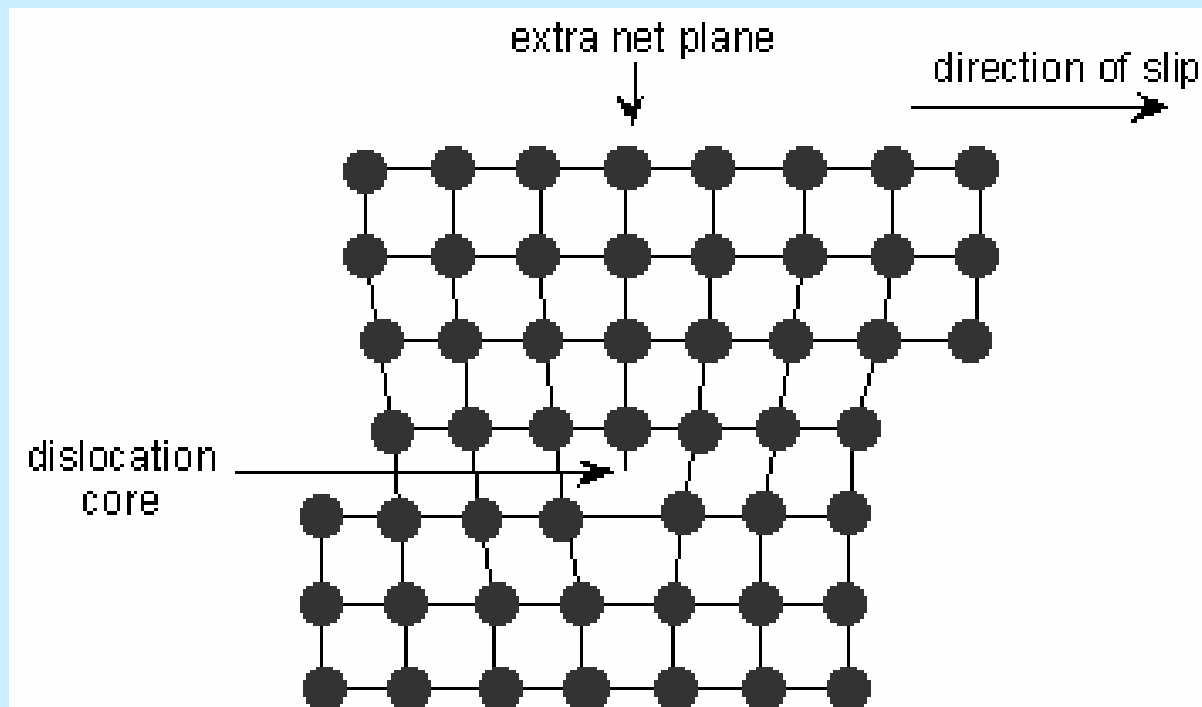
Line imperfections in a 3D lattice

- Edge
- Screw
- Mixed

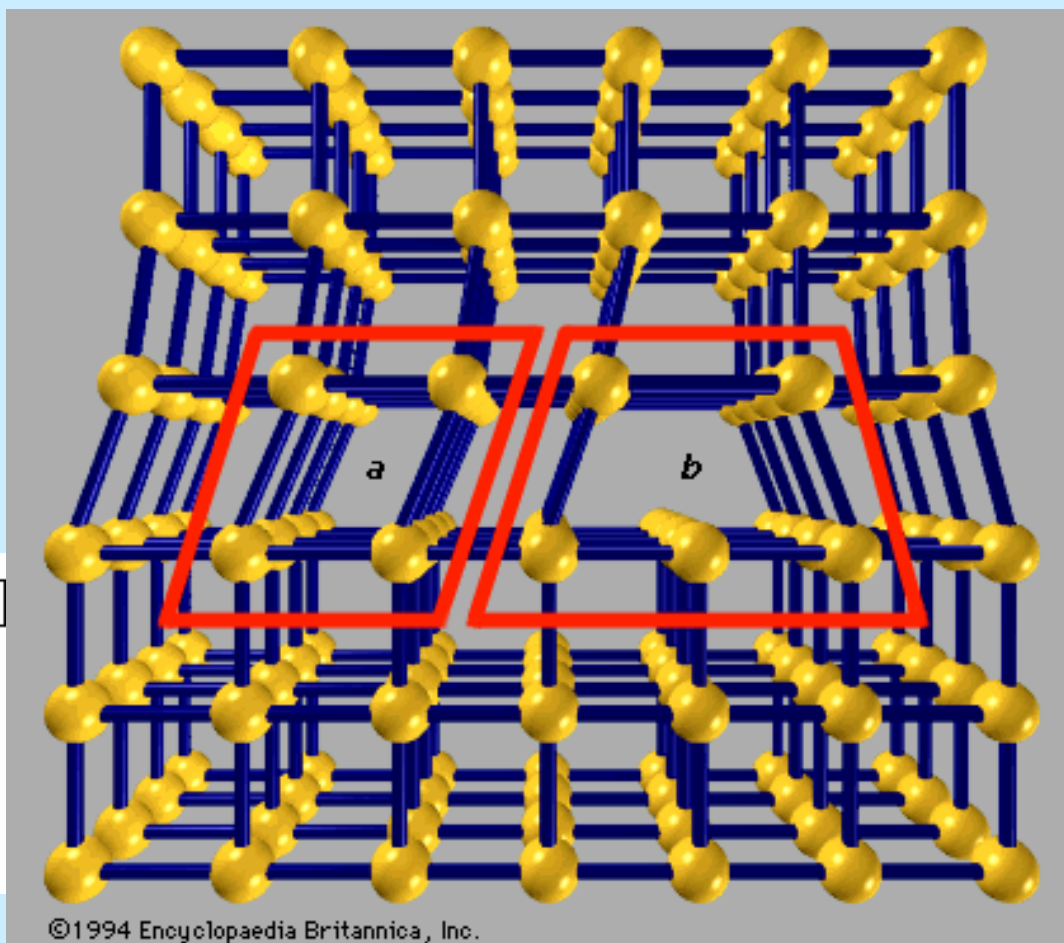
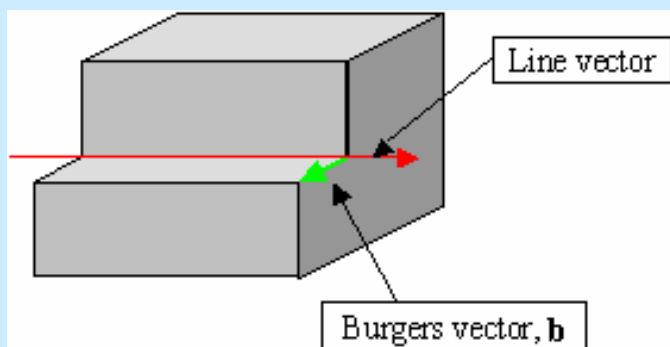
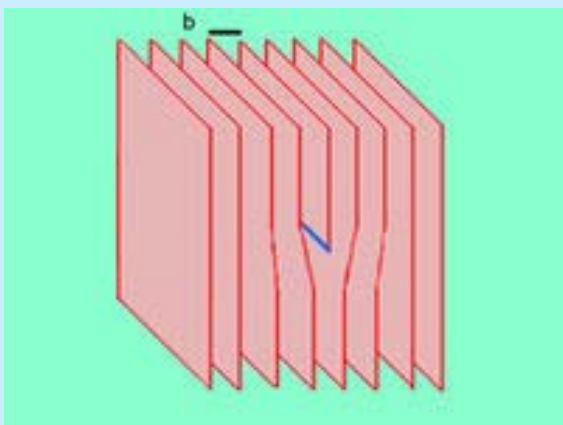


Edge Dislocation

- Extra plane of atoms
- Burgers vector
 - Deformation direction
 - For edge dislocations it is perpendicular to the dislocation line

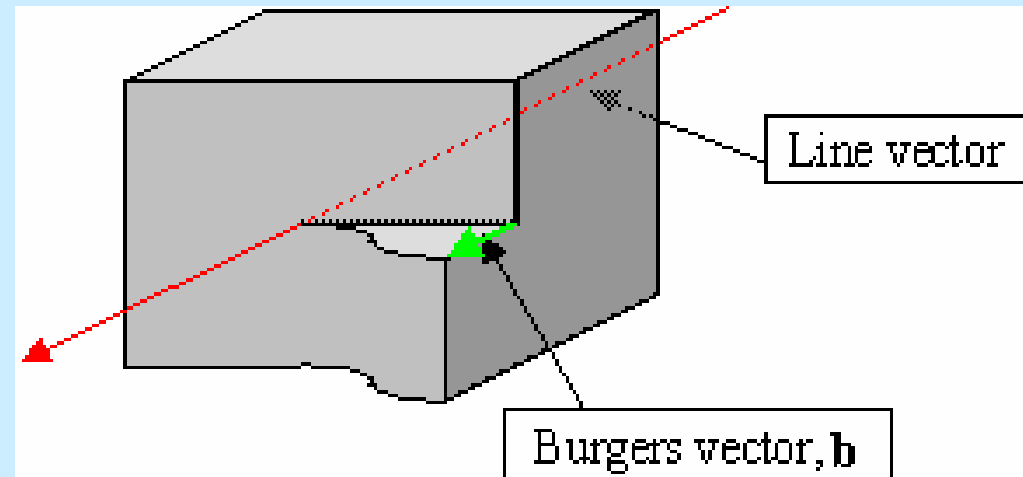
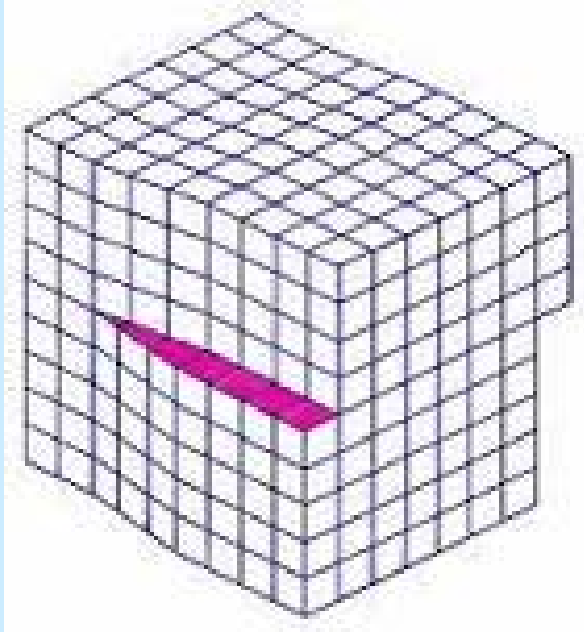


Edge Dislocation

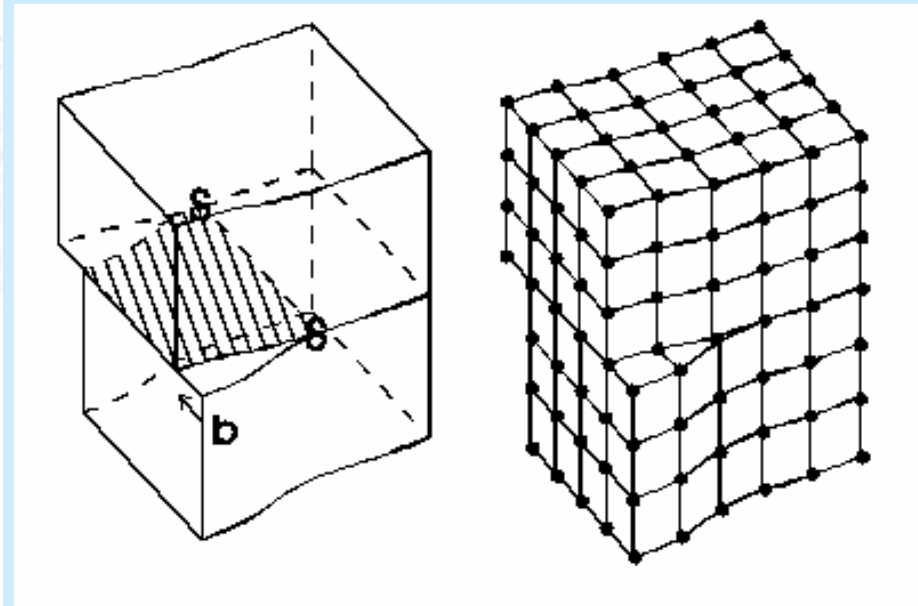
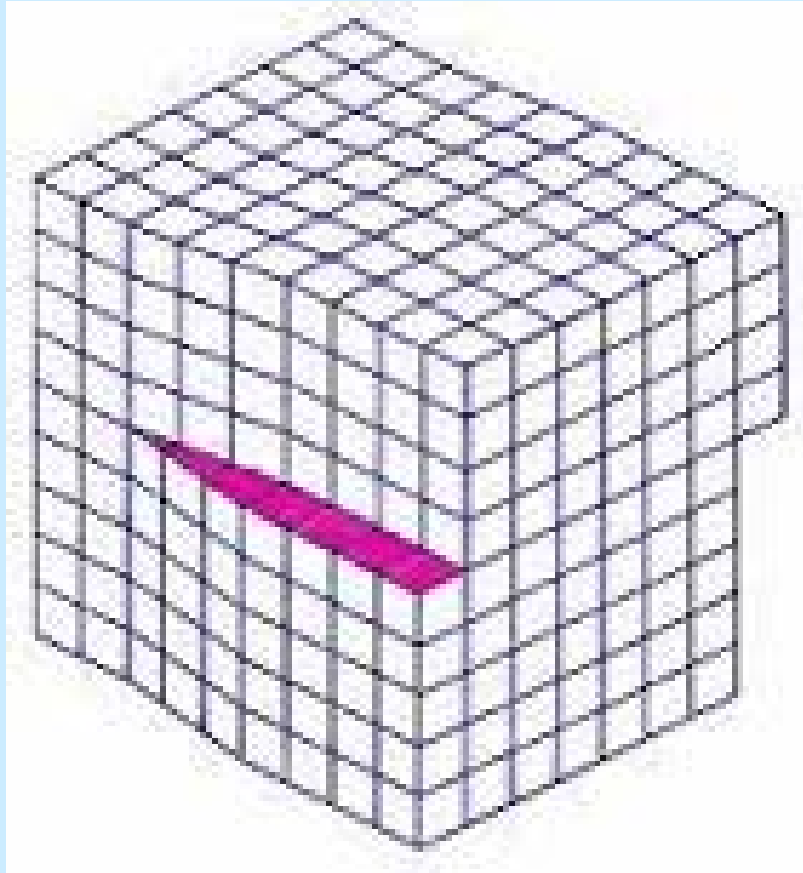


Screw Dislocation

- A ramped step
- Burgers vector
 - Direction of the displacement of the atoms
 - For a screw dislocation it is parallel to the line of the dislocation



Screw Dislocation



Deformation

When a shear force is applied to a material, the dislocations move
Plastic deformation in a material occurs due to the movement of dislocations (linear defects)

The strength of the material depends on the force required to make the dislocation move, not the bonding energy

Millions of dislocations result from plastic forming operations such as rolling and extruding

Any defect in the regular lattice structure (point, planar defects, other dislocations) disrupts the motion of dislocation - makes slip or plastic deformation more difficult

Deformation

Dislocation movement produces additional dislocations

Dislocations collide – entangle – impede movement of other dislocations - drives up the force needed to move the dislocation - strengthens the material

Applying a force to the material increases the number of dislocations

Called “strain hardening” or “cold work”

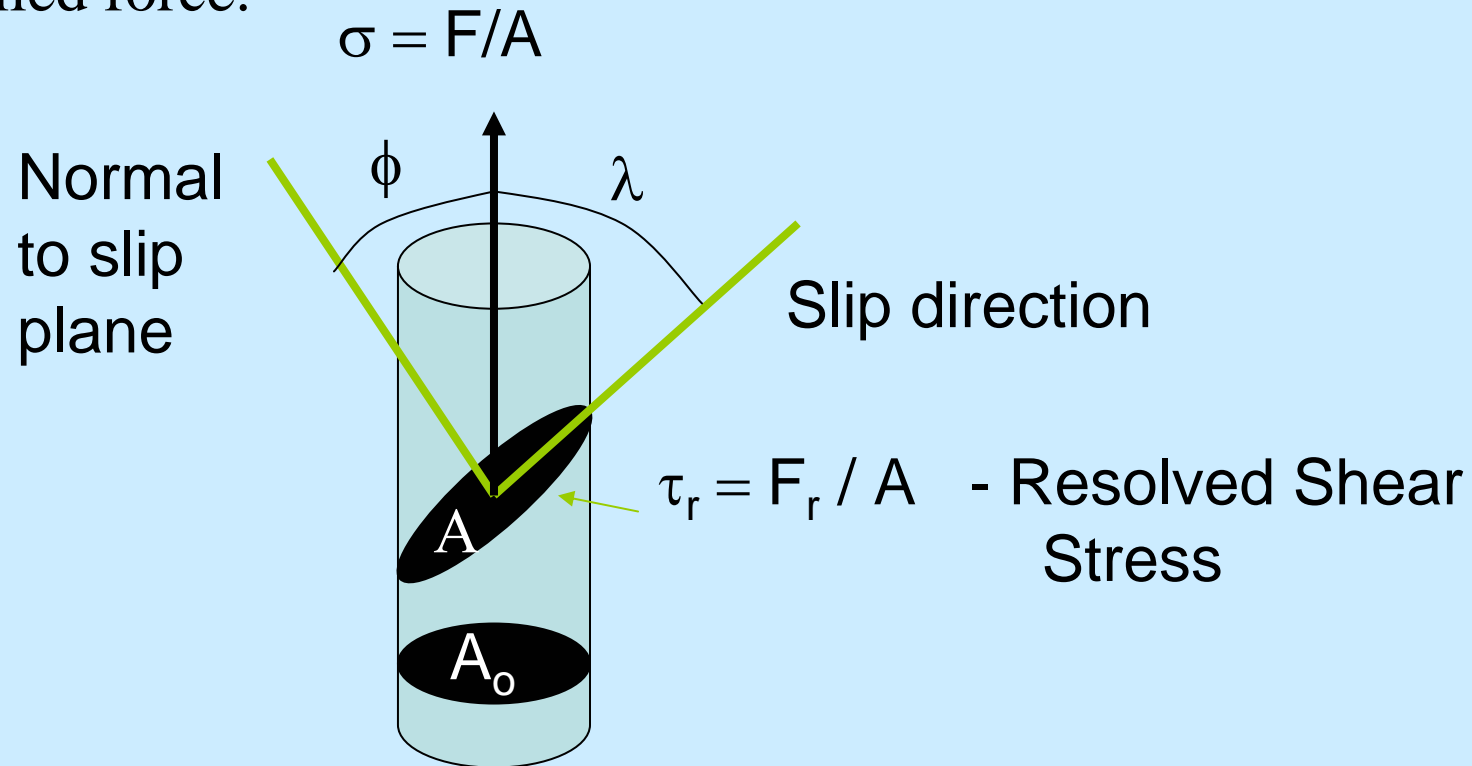
Slip

- When dislocations move slip occurs
 - Direction of movement – same as the Burgers vector
- Slip is easiest on close packed **planes**
- Slip is easiest in the close packed **direction**

- Affects
 - Ductility
 - Material Strength

Schmidt's Law

- In order for a dislocation to move in its slip system, a shear force acting in the slip direction must be produced by the applied force.



Schmidt's Law

- $F_r = F \cos(\lambda)$

$$A = A_0 / \cos(\phi)$$

$$\tau = \sigma \cos(\phi) \cos(\lambda)$$

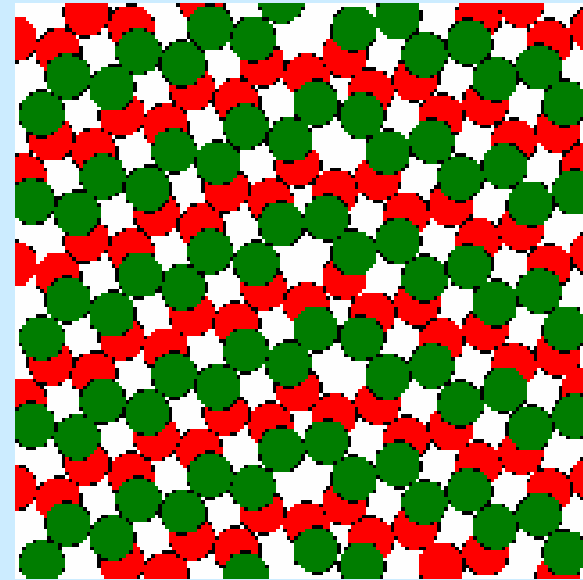
Where:

$\tau = F_r / A =$ resolved shear stress in the slip direction

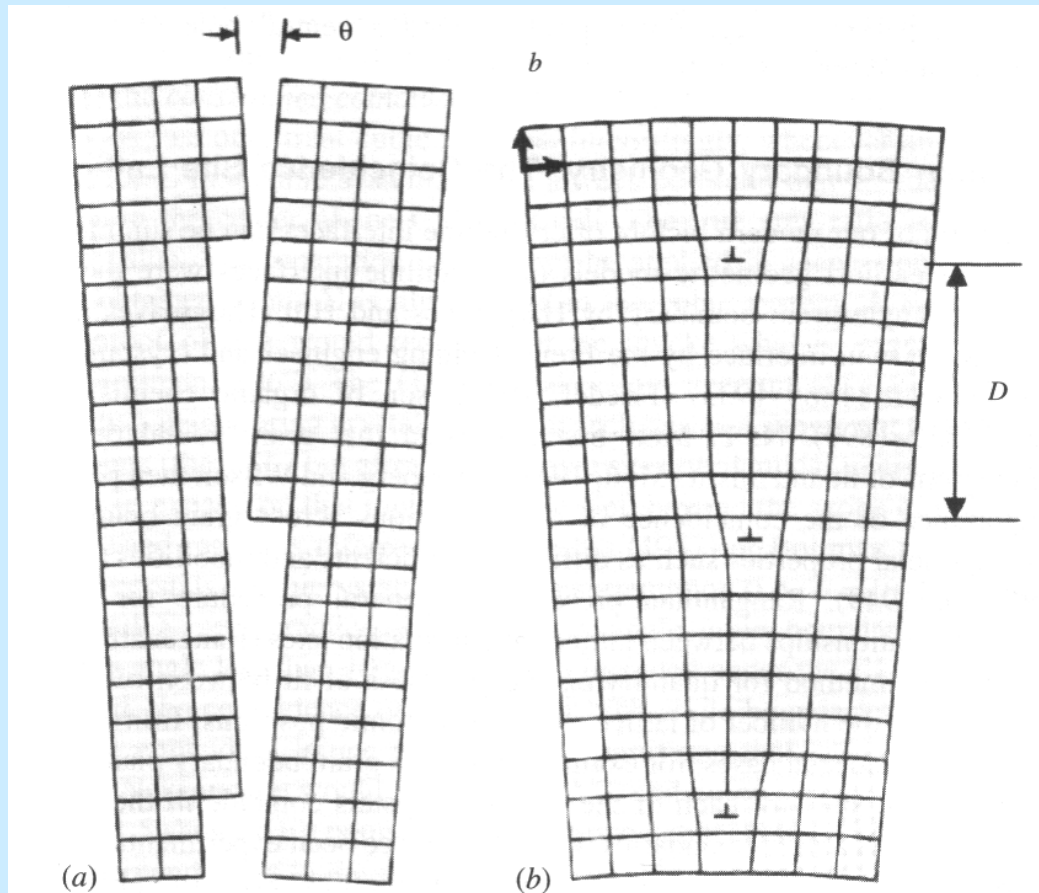
$\sigma = F/A_0 =$ unidirectional stress applied to the cylinder

Surface and Grain Boundaries

- The atoms at the boundary of a grain or on the surface are not surrounded by other atoms – lower CN, weaker bonding
- Grains line up imperfectly where the grain boundaries meet
- Dislocations can usually not cross grain boundaries
- Tilt and Twist boundaries
- Low and High angle boundaries



Low Angle Tilt Boundary

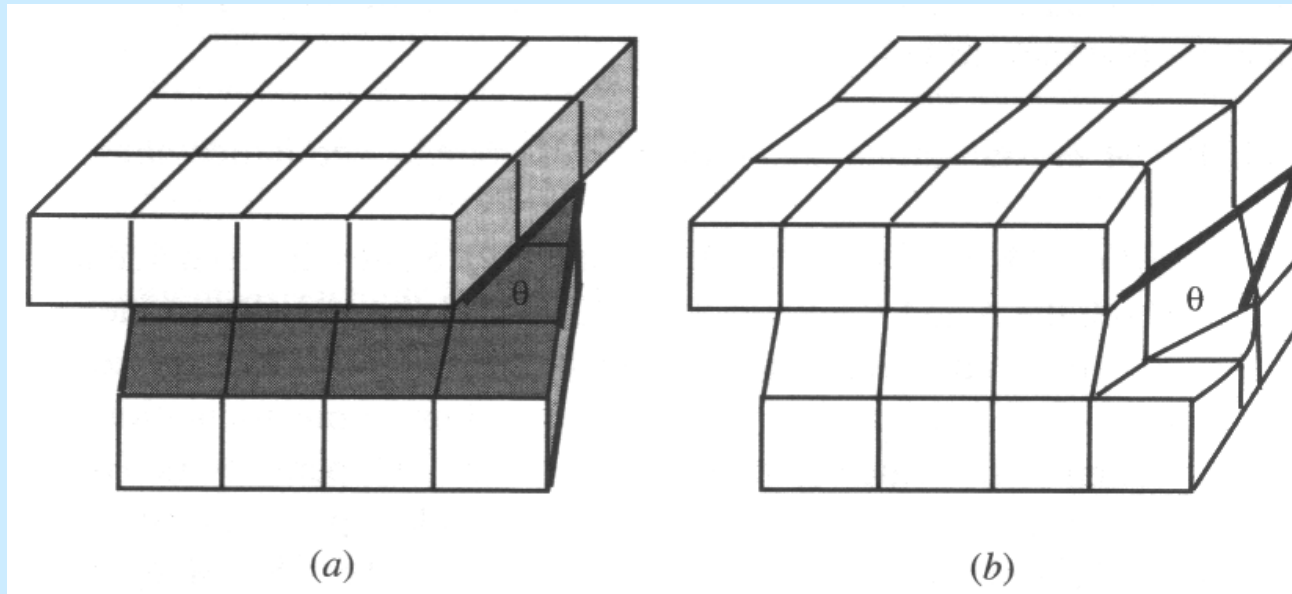


**Low Angle Tilt Boundary =
Array of Edge dislocations**

$$D = \frac{b}{\sin \theta}$$

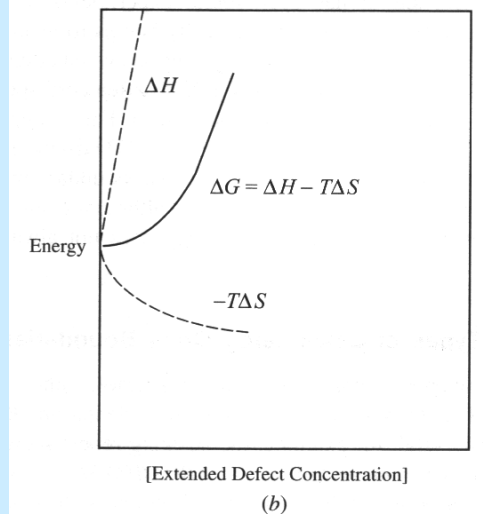
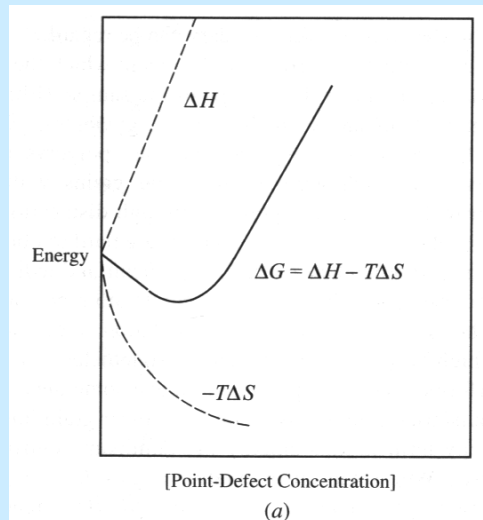
D = dislocation spacing
b = Burgers vector
 θ = misorientation angle

Low Angle Twist Boundary



**Low Angle Twist Boundary = a
Screw dislocation**

Crystal Energies



**Point defects = equilibrium concentration,
Enthalpy is positive, configurational entropy positive
Minimum on free energy**

**Extended defects = no equilibrium concentration,
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entropy cannot outweigh, no minimum on free
energy**

Metastable – dislocations, grain boundaries, surface

Heating - minimize free energy:

polycrystalline → single crystal grain growth

Grains with high dislocation density consumed

Atoms move across grain boundary

Effect of Grain Size on Strength

- In a small grain, a dislocation gets to the boundary and stops – slip stops
- In a large grain, the dislocation can travel farther
- Small grain size equates to more strength

Hall-Petch Equation

$$\sigma_y = \sigma_0 + K d^{-1/2}$$

σ_y = yield strength (stress at which the material permanently deforms)

d = average diameter of the grains

σ_0 = constant

K = constant

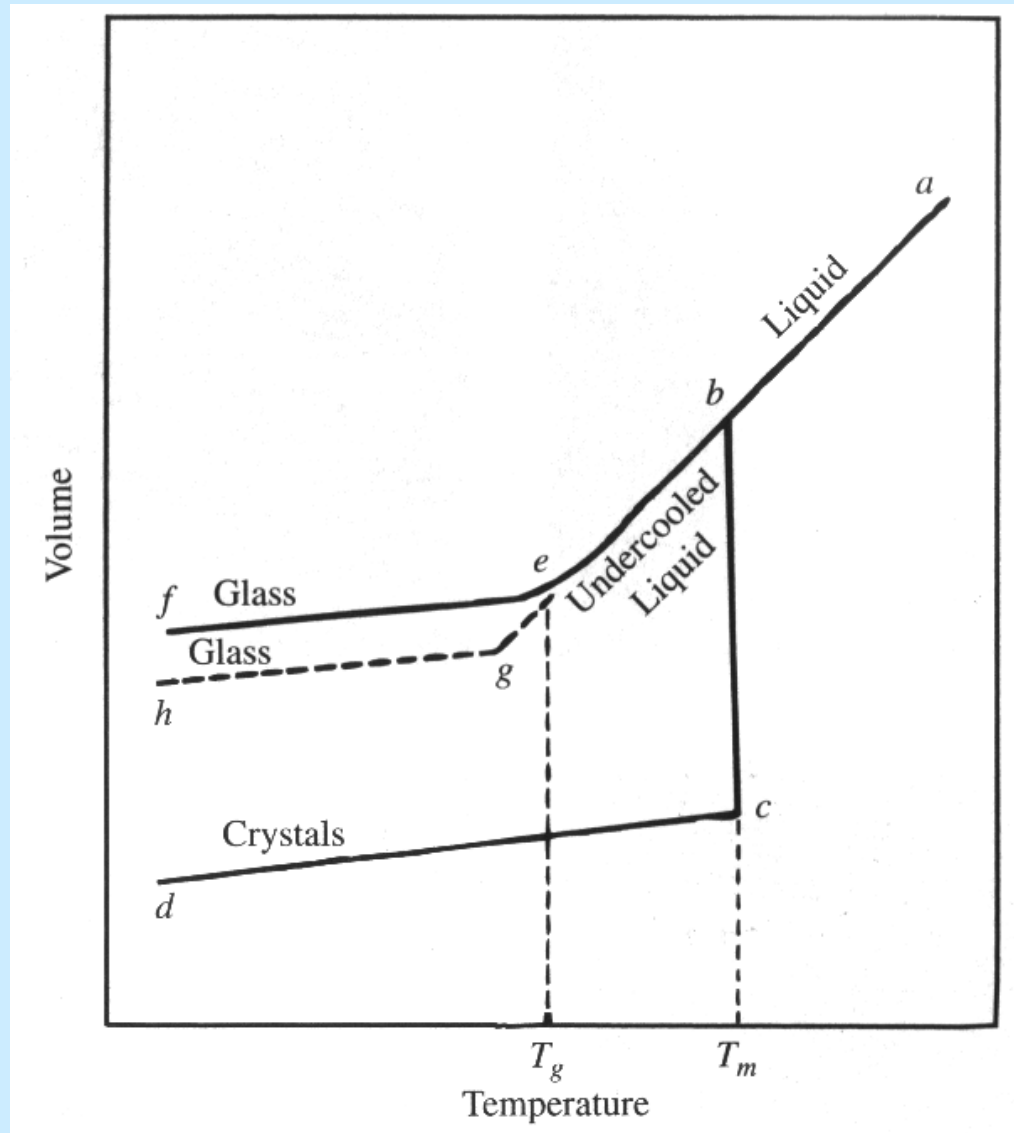
Control of the Slip Process

- Strain hardening
- Solid Solution strengthening
- Grain Size strengthening

Amorphous Structures

- Cooling a material off too fast - it does not have a chance to crystallize
- Forms a glass
- Easy to make a ceramic glass
- Hard to make a metallic glass
- There are no slip planes, grain boundaries in a glass

Amorphous Structures



Diffusion

Velocity of diffusion of particles (ions, atoms ...) in a solid

- mass transport and concentration gradient for a given point in a solid!

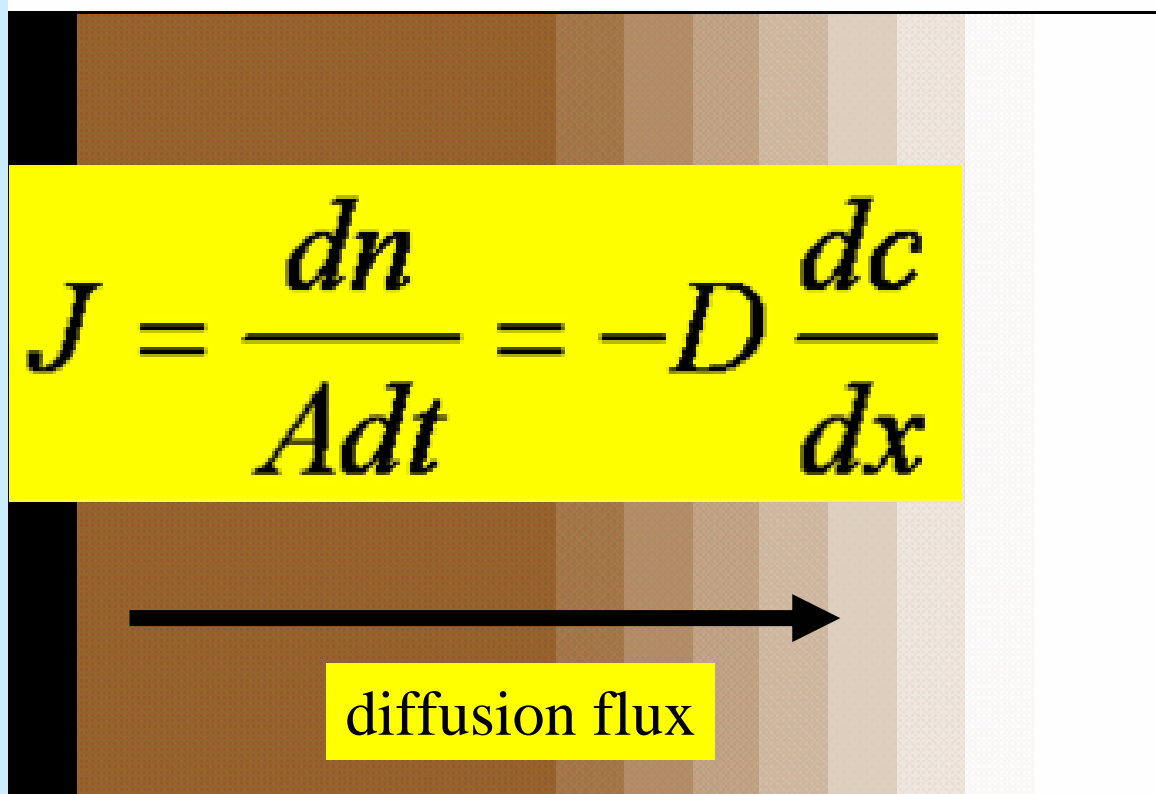
$$J = \frac{dn}{A dt} = -D \frac{dc}{dx} \quad [\text{mol cm}^{-2} \text{s}^{-1}] \quad (\text{const. T})$$

J_i : flow of diffusion ($\text{mol s}^{-1} \text{cm}^{-2}$); D_i : diffusion coefficient ($\text{cm}^2 \text{s}^{-1}$)

$\delta c_i / \delta x$: concentration gradient ($\text{mol cm}^{-3} \text{cm}^{-1}$) (i.e. change of concentration along a line in the solid!)

Diffusion - Fick's First Law

Fick's first law describes steady state diffusion



J = diffusion flux
[mol s⁻¹ m⁻²]

D = diffusion coefficient
diffusivity
[m² s⁻¹]

dc/dx = concentration
gradient

A = area [m²]

x

Typical diffusion coefficients for ions (atoms) in a solid at room temperature are about $10^{-13} \text{ cm}^2 \text{ s}^{-1}$.

In solid state ionic conductors (e.g. Ag-ions in α -AgI) the values are greater by orders of magnitude ($\approx 10^{-6} \text{ cm}^2 \text{ s}^{-1}$)

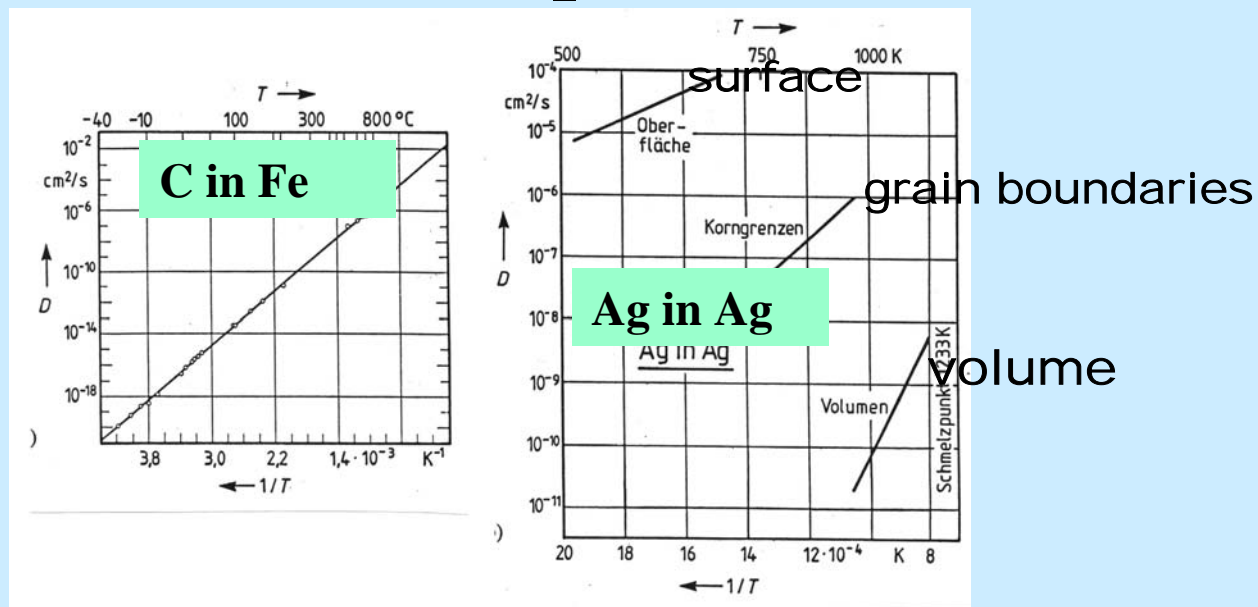
Knowledge of D allows an estimation of the average diffusion length for the migrating particles:

$$\langle x^2 \rangle = 2Dt \quad (\langle x^2 \rangle: \text{average square of diffusion area; } t: \text{time})$$

Diffusion coefficients show an exponential temperature dependence (Arrhenius type):

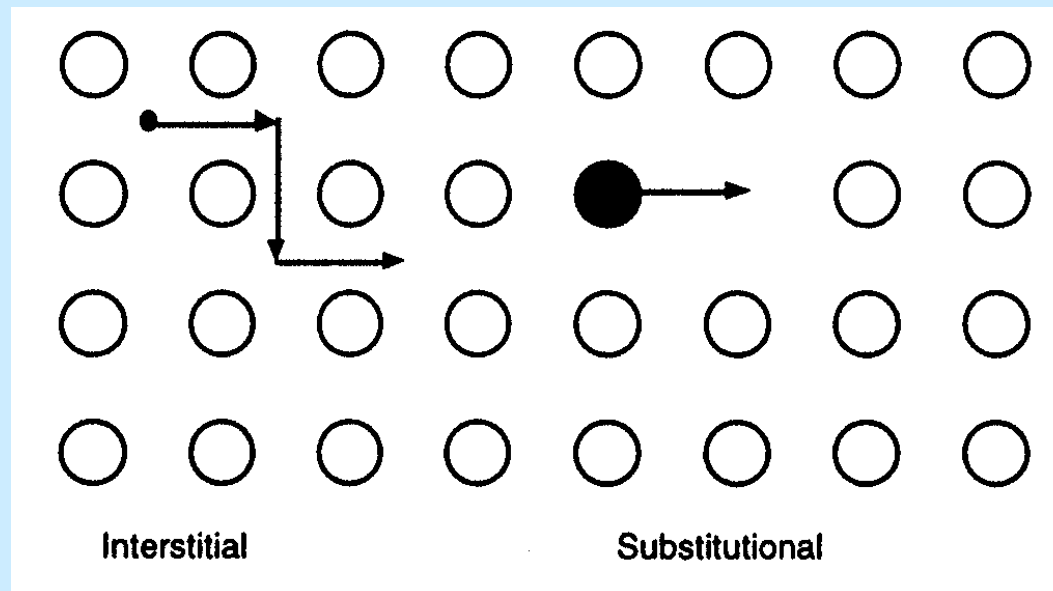
$$D = D_{\infty} \exp(-Q/kT) \quad (D_{\infty}: D \text{ for } T \rightarrow \infty, Q: \text{activation energy of diffusion, } k: \text{Boltzmann-faktor})$$

The logarithmic representation of D versus $1/T$ is linear, the slope corresponds to the activation energy and the intercept to D_{∞} .

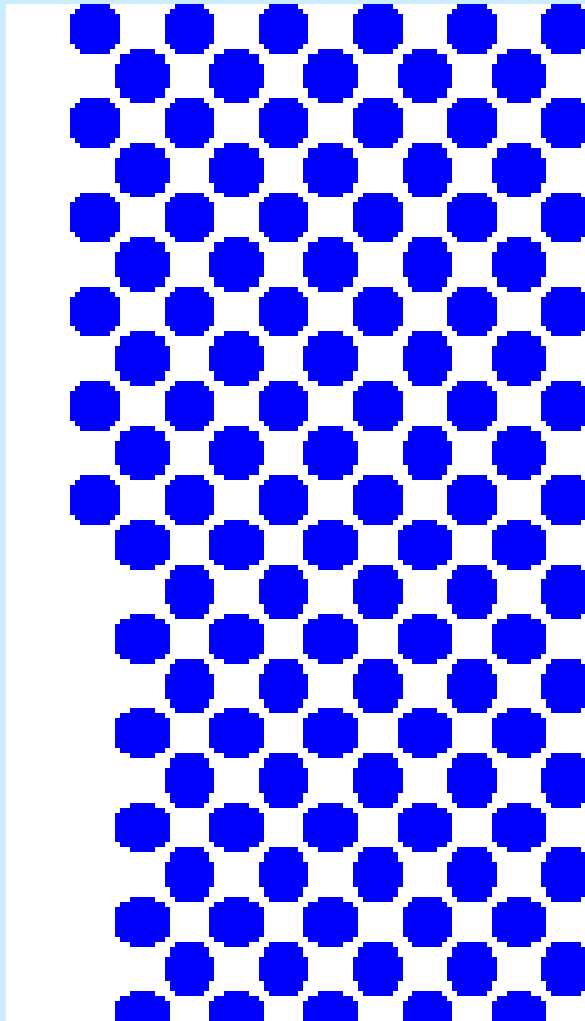


Mechanics of Diffusion

- Primarily At Defects
 - Point Defects
 - Line Defects
 - Edge Defects
- Through Interstitial Spaces

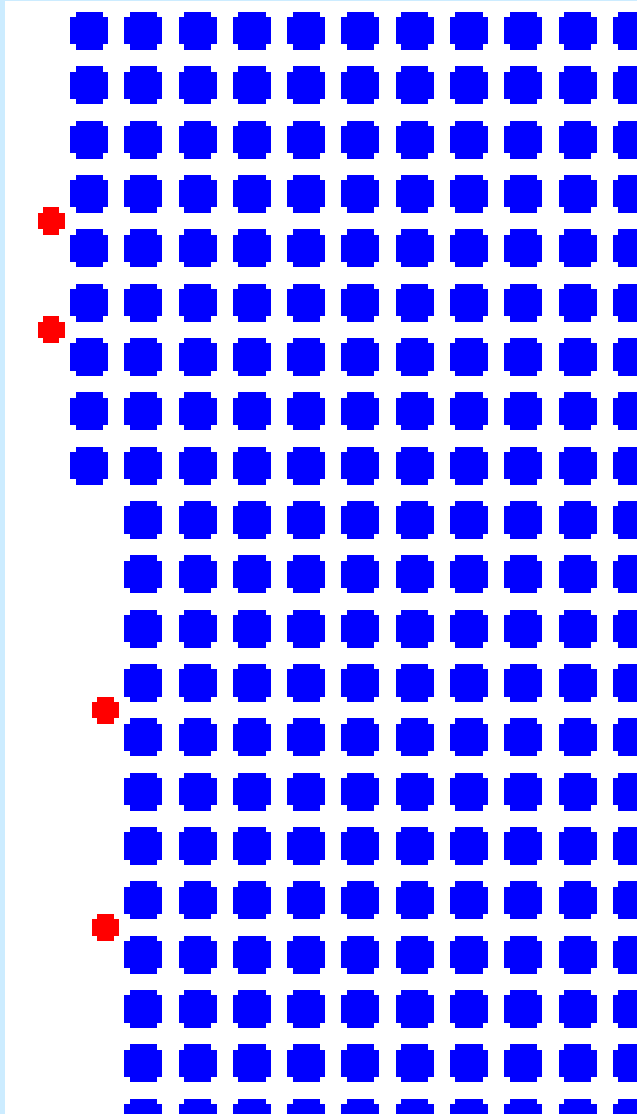


Vacancy Diffusion



- Vacancies are holes in the matrix
- Vacancies are always moving
- An impurity can move into the vacancy
- Diffuse through the material

Interstitial Diffusion



- There are holes between the atoms in the matrix
- If the atoms are small enough, they can diffuse through the interstitial holes
- Fast!!

Other Mechanisms

- Grain Boundaries
- Surface

Activation Energy

- All the kinds of diffusion require a certain minimum energy to occur
- The activation energy
- The higher the activation energy, the harder it is for diffusion to occur
- The highest energy is for volume diffusion
 - Vacancy
 - Interstitial
- Grain Boundary diffusion requires less energy
- Surface Diffusion requires the least

Diffusion Rate

- High activation energy corresponds to low diffusion rates
- $D = D_0 \cdot \exp(-Q/RT)$
 - Where D is the diffusivity, which is proportional to the diffusion rate
 - Q is the activation energy
 - R is the gas constant
 - T is the absolute temperature

Diffusivity

- D is a function of temperature
- Thus the flux (J) is also a function of temperature

